AMENDMENTS TO THE CLAIMS:

The following listing of claims replaces all prior listings, and all prior versions, of claims in the application:

LISTING OF CLAIMS:

1. (Previously presented) An encapsulating solid epoxy resin molding material, comprising (A) an epoxy resin, (B) a curing agent, and (C) a silica,

wherein (C) the silica has a maximum diameter size of at least 32 μm, an average particle size of 12 μm or less and a specific surface area of 3.0 m^2/g or more, and

wherein (C) the silica satisfies the following conditions: the amount of particles having a particle size of 12 μm or less is 50% or more by weight; the amount of particles having a particle size of 24 μm or less is 70% or more by weight; and the amount of particles having a particle size of 32 μm or less is 80% or more by weight; the amount of particles having a particle size of 48 μm or less is 90% or more by weight.

2. (Previously presented) An encapsulating solid epoxy resin molding material, comprising (A) an epoxy resin, (B) a curing agent, and (C) a silica,

wherein (C) the silica comprises 5% or more by weight of silica having a maximum particle size of 63 μm or less and particle sizes of 20 μm or more.

3. (Cancelled).

4. (Previously presented) An encapsulating solid epoxy resin molding material, comprising (A) an epoxy resin, (B) a curing agent, and (C) an inorganic filler, and satisfying all of the following conditions: the glass transition temperature based on TMA method is 150°C or higher; the bending modulus based on JIS-K 6911 is 19 GPa or less; and the mold shrinkage ratio based on JIS-K 6911 is 0.2% or less.

5. (Previously presented) The encapsulating solid epoxy resin molding material according to claim 1, wherein the melt viscosity of the epoxy resin (A) is 2 poises or less at 150°C.

6. (Previously presented) The encapsulating solid epoxy resin molding material according to claim 1, wherein the epoxy resin (A) comprises at least one of a biphenyl epoxy resin, a bisphenol F epoxy resin, a stylbene epoxy resin, a sulfur-containing epoxy resin, a Novolak epoxy resin, a dicyclopentadiene epoxy resin, a naphthalene epoxy resin and a triphenylmethane epoxy resin.

7. (Previously presented) The encapsulating solid epoxy resin molding material according to claim 1, wherein the melt viscosity of the curing agent (B) is 2 poises or less at 150°C.

8. (Previously presented) The encapsulating solid epoxy resin molding material according to claim 1, wherein the curing agent (B) comprises at least one of

a biphenyl phenol resin, an aralkyl phenol resin, a dicyclopentadiene phenol resin, a triphenylmethane phenol resin, and a Novolak phenol resin.

9. (Previously presented) The encapsulating solid epoxy resin molding material according to claim 1, further comprising a curing accelerator (F).

10. (Cancelled).

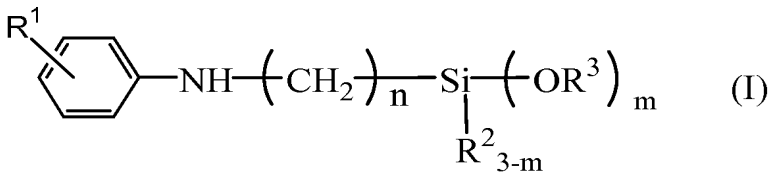
11. (Previously presented) The encapsulating solid epoxy resin molding material according to claim 1, wherein the average particle size of (C) the silica is 10 μm or less.

12. (Previously presented) The encapsulating solid epoxy resin molding material according to claim 1, wherein the specific surface area of (C) the silica is from 3.5 to 5.5 m^2/g.

13. (Previously presented) The encapsulating solid epoxy resin molding material according to claim 1, further comprising a coupling agent(D).

14. (Previously presented) The encapsulating solid epoxy resin molding material according to claim 13, wherein the coupling agent (D) comprises (D2) a silane coupling agent having a secondary amino group.

15. (Previously presented) The encapsulating solid epoxy resin molding material according to claim 14, wherein the silane coupling agent (D2), which has the secondary amino group, comprises a compound represented by the following general formula (I):



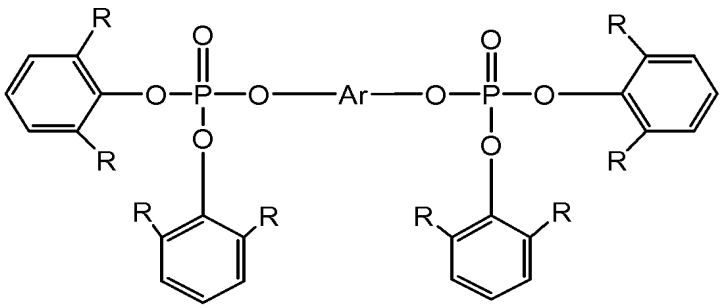
(I)

wherein R^1 is selected from a hydrogen atom, an alkyl group having 1 to 6 carbon atoms, and an alkoxy group having 1 to 2 carbon atoms, R^2 is selected from an alkyl group having 1 to 6 carbon atoms, and a phenyl group, R^3 represents a methyl or ethyl group, n represents an integer of 1 to 6, and m represents an integer of 1 to 3.

16. (Previously presented) The encapsulating solid epoxy resin molding material according to claim 1, further comprising a phosphorus compound (E).

17. (Previously presented) The encapsulating solid epoxy resin molding material according to claim 16, wherein the phosphorus compound (E) comprises a phosphate.

18. (Previously presented) The encapsulating solid epoxy resin molding material according to claim 17, wherein the phosphate comprises a compound represented by the following general formula (II):

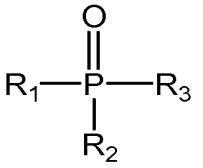


(II)

wherein eight R's, which may be the same or different, each represent an alkyl group having 1 to 4 carbon atoms, and Ar represents an aromatic ring.

19. (Previously presented) The encapsulating solid epoxy resin molding material according to claim 16, wherein the phosphorus compound (E) comprises phosphine oxide.

20. (Previously presented) The encapsulating solid epoxy resin molding material according to claim 19, wherein the phosphine oxide comprises a compound represented by the following general formula (III):



(III)

wherein R^1, R^2 and R^3, which may be the same or different, each represent a substituted or unsubstituted alkyl group having 1 to 10 carbon atoms, an aryl group, an aralkyl group, or a hydrogen atom provided that the case that all of R^1, R^2 and R^3 are hydrogen atoms is excluded.

21. and 22. (Cancelled).

23. (Previously presented) The encapsulating solid epoxy resin molding material according to claim 13, wherein the filler coverage ratio of the coupling agent (D) is from 0.3 to 1.0.

24. (Previously presented) The encapsulating solid epoxy resin molding material according to claim 13, wherein the heating loss ratio after heating at 200°C/hour is 0.25% or less by weight.

25. (Previously presented) The encapsulating solid epoxy resin molding material according to claim 23, wherein the heating loss ratio after heating at 200°C/hour is 0.25% or less by weight.

26. and 27. (Cancelled).

28. (Previously presented) The encapsulating solid epoxy resin molding material according to claim 4, wherein the warp of a semiconductor device is 5.0 mm or less.

29. (Previously presented) The encapsulating solid epoxy resin molding material according to claim 4, wherein the warp of a semiconductor device is 2.0 mm or less.

30. (Previously presented) The encapsulating solid epoxy resin molding material according to claim 4, wherein the content by percentage of the inorganic filler (C) is from 70 to 90% by weight of the epoxy resin molding material.

31. (Currently amended) A semiconductor device encapsulated by ~~an encapsulating solid epoxy resin molding material comprising (A) an epoxy resin, (B) a curing agent, and (C) an inorganic filler~~the encapsulating solid epoxy resin molding material according to claim 1.

32.-35. (Cancelled).